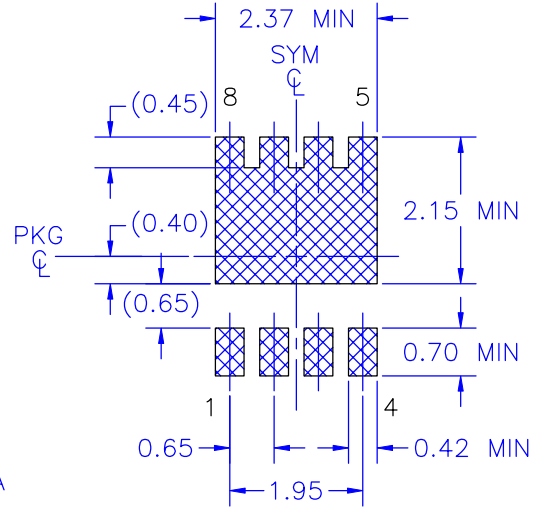
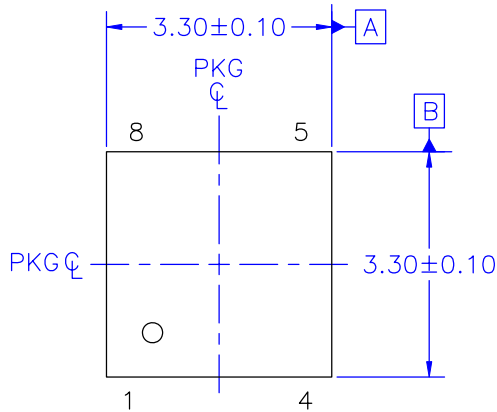
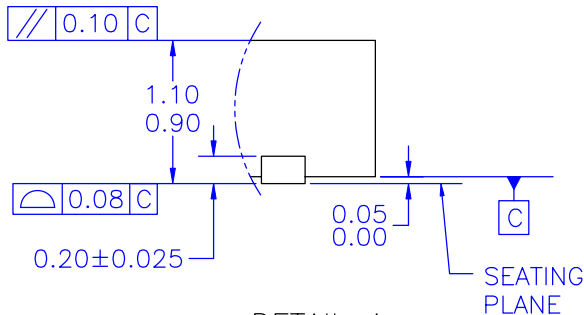
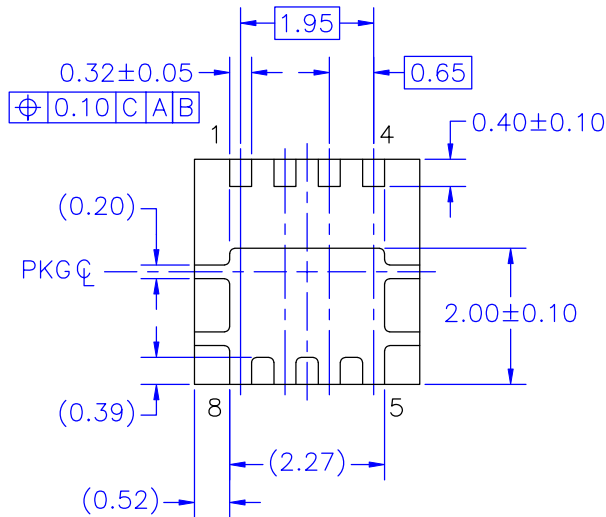
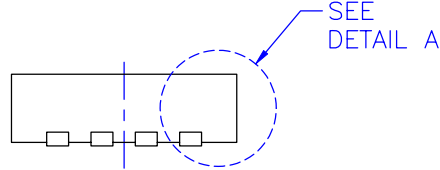


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REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
1	RELEASE TO DOCUMENT CONTROL	CB/259/06	20DEC2006
			MRG



LAND PATTERN RECOMMENDATION



DETAIL A
SCALE: 2X

APPROVED
19-January-2008

NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08BREV1

PQFN08BREV1

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™	
DRAWN: J.P. GOMEZ	27DEC2007	CEBU PHILIPPINES	
CHECKED: C.B. ESTACIO		8LD, PQFN, DUAL, JEDEC MO-240 BA, 3.3X3.3MM, SINGLE TIED DAP	
APPROVED: M.R. GESTOLE		SCALE: 1:1	SIZE: NA
G.S. BAJE		DRAWING NUMBER: MKT-PQFN08B	REV: 1
PROJECTION		FORMERLY: N/A	SHEET: 1 OF 1